SI2301

P-Channel Enhancement Mode MOSFET

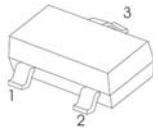
V_{DSS}	-20 V
I_D	-3.0 A
$R_{DS(ON)}$	55 m Ω

FEATURES

- High density cell design for low $R_{DS(ON)}$
- Voltage controlled small signal switch
- Rugged and reliable
- High saturation current capability

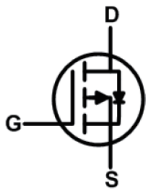
A1SHB

SOT-23



1. GATE
2. SOURCE
3. DRAIN

Equivalent Circuit



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Maximum ratings (T_a=25℃ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	±12	
Continuous Drain Current	I_D	-3	A
Pulsed Drain Current	I_{DM}	-10	
Continuous Source-Drain Diode Current	I_S	-0.72	
Maximum Power Dissipation	P_D	1.2	W
Thermal Resistance from Junction to Ambient(t ≤5s)	$R_{\theta JA}$	357	℃/W
Junction Temperature	T_J	150	℃
Storage Temperature	T_{stg}	-55 ~+150	

Electrical characteristics (T_a=25℃ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Static						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D =-250μA	-20			V
Gate-source threshold voltage	$V_{GS(th)}$	V_{DS} =V_{GS}, I_D =-250μA	-0.4		-1	
Gate-source leakage	I_{GSS}	V_{DS} =0V, V_{GS} =±8V			±100	nA
Zero gate voltage drain current	I_{DSS}	V_{DS} =-20V, V_{GS} =0V			-1	μA
Drain-source on-state resistance [a]	$R_{DS(on)}$	V_{GS} =-4.5V, I_D =-3A		0.055	0.080	Ω
		V_{GS} =-2.5V, I_D =-2.0A		0.080	0.122	
Forward transconductance [a]	g_{fs}	V_{DS} =-5V, I_D =-3A		6.5		S
Dynamic[b]						
Input capacitance	C_{iss}	V_{DS} =-10V,V_{GS} =0V,f =1MHz		405		pF
Output capacitance	C_{oss}			75		
Reverse transfer capacitance	C_{rss}			55		
Total gate charge	Q_g	V_{DS} =-10V,V_{GS} =-4.5V,I_D =-3A		5.5	10	nC
		V_{DS} =-10V,V_{GS} =-2.5V,I_D =-3A		3.3	6	
Gate-source charge	Q_{gs}			0.7		
Gate-drain charge	Q_{gd}			1.3		
Gate resistance	R_g	f =1MHz		6.0		Ω
Turn-on delay time	$t_{d(on)}$	V_{DD}=-10V, R_L=10Ω, I_D =-1A, V_{GEN}=-4.5V,Rg=1Ω		11	20	ns
Rise time	t_r			35	60	
Turn-off delay time	$t_{d(off)}$			30	50	
Fall time	t_f			10	20	
Drain-source body diode characteristics						
Continuous source-drain diode current	I_S	T_C=25℃			-1.3	A
Pulse diode forward current [a]	I_{SM}				-10	
Body diode voltage	V_{SD}	I_S=-0.7A		-0.8	-1.2	V

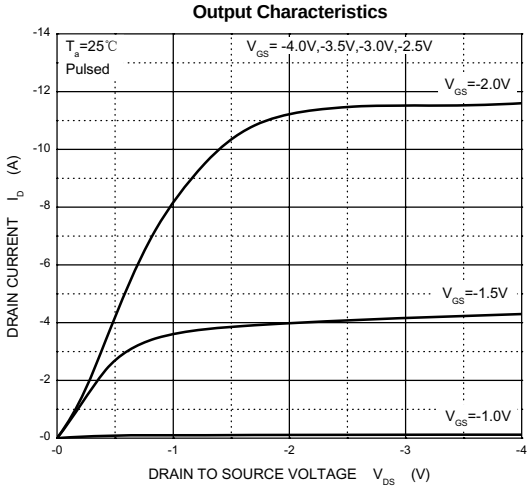
Notes :

a.Pulse Test : Pulse Width < 300μs, Duty Cycle ≤2%.

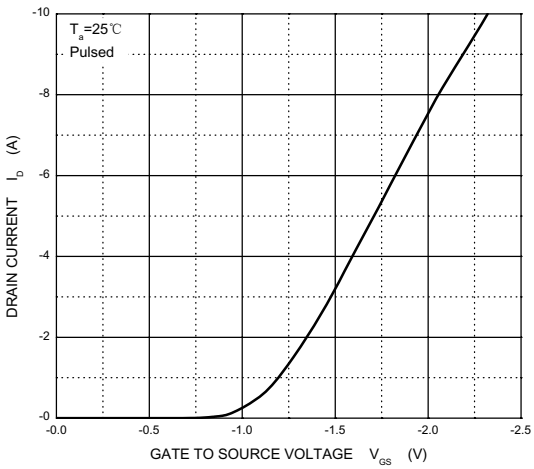
b.Guaranteed by design, not subject to production testing.

RATING AND CHARACTERISTIC CURVES

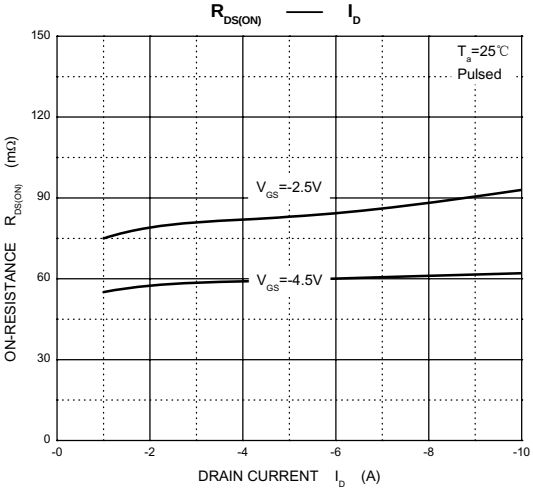
Output Characteristics



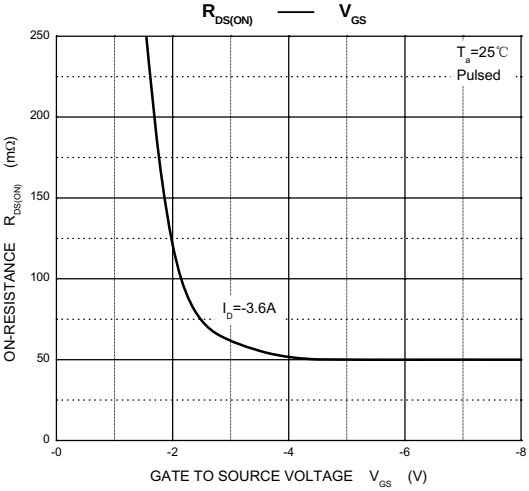
Transfer Characteristics



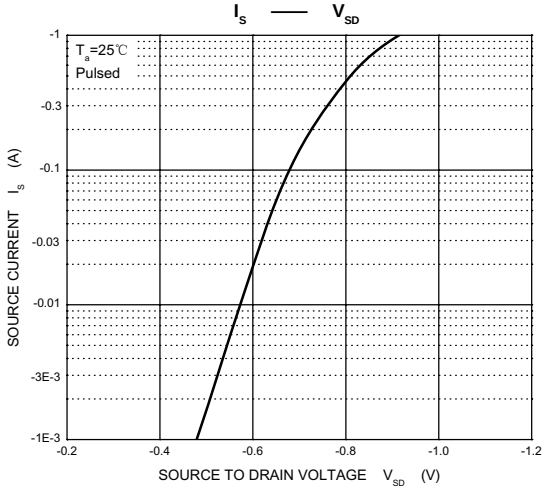
$R_{DS(ON)}$ —— I_D



$R_{DS(ON)}$ —— V_{GS}



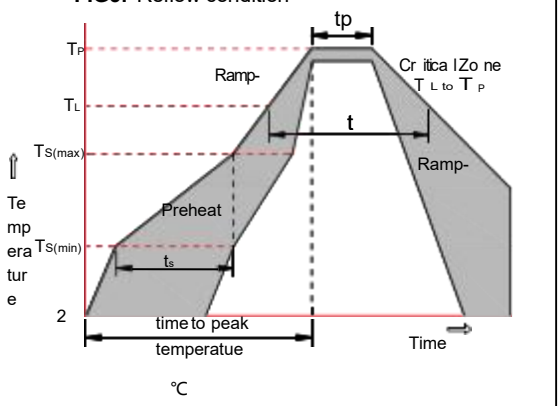
I_S —— V_{SD}



Soldering parameters

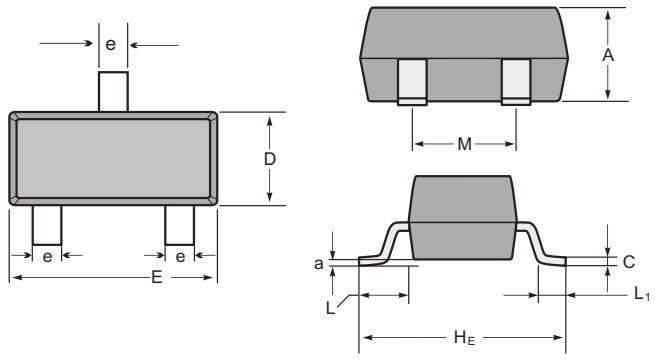
Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃ of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃

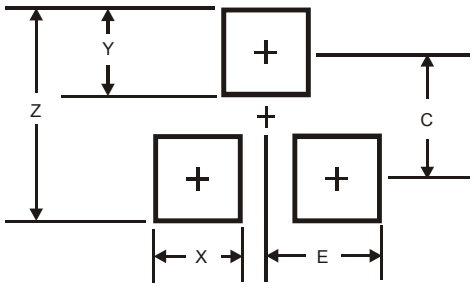
FIG5: Reflow condition



Package Dimensions & Suggested Pad Layout

SOT23





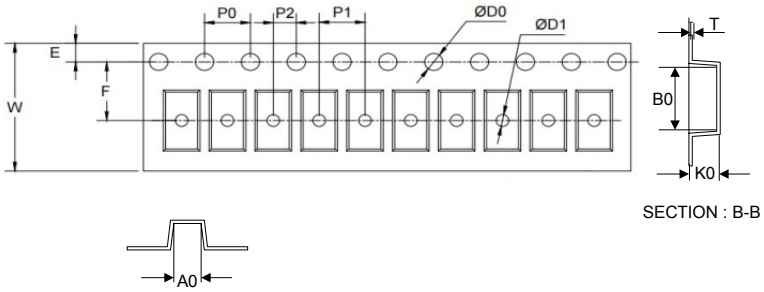
SOT-23 mechanical data

UNIT		A	C	D	E	H_E	e	M	L	L_1	a
mm	max	1.1	0.15	1.4	3.0	2.6	0.5	1.95	0.55 (ref)	0.36 (ref)	0.0
	min	0.9	0.08	1.2	2.8	2.2	0.3	1.7			0.15
mil	max	43	6	55	118	102	20	77	22 (ref)	14 (ref)	0.0
	min	35	3	47	110	87	12	67			6

Dimensions	SOT23
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

Tape & rell specification

Tape

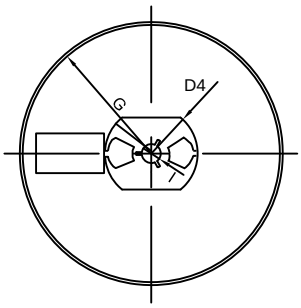


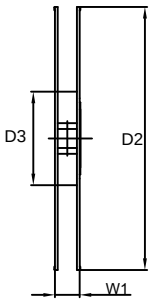
SECTION : B-B

SECTION : A-A

Symbol	Dimension (mm)
P0	4.00±0.10
P1	4.00±0.10
P2	2.00±0.10
D0	1.55±0.10
D1	1.05±0.10
E	1.55±0.10
F	3.60±0.10
W	8.00±0.10
A0	3.80±0.20
B0	3.25±0.20
K0	1.45±0.10
T	0.25±0.05

7” Reel





D2	178.0±3.0
D3	55Min.
D4	R24.0±3.0
G	R82.0±3.0
I	13.0±2.0
W1	11.0±3.0

Quantity: 3000PCS